

**650V,10A,160mΩ GaN HEMT****Contents**

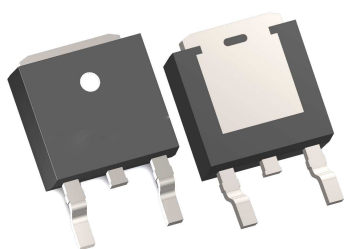
1. Features .....	2
2. Device Information.....	2
3. Applications .....	3
4. Description.....	3
5. Absolute Maximum Ratings (Tc=25°C unless otherwise specified).....	3
6. Electrical Characteristics (Tc=25°C unless otherwise specified).....	4
6.1 Typical Performance – Static.....	4
6.2 Typical Performance – Dynamic.....	5
6.3 Characteristic Curve.....	5
7. Package.....	7
7.1 TO252 .....	7
7.2 DFN5x6 .....	8
7.3 PDDFN4x4 .....	9
7.4 DFN8x8 .....	10

## 1. Features

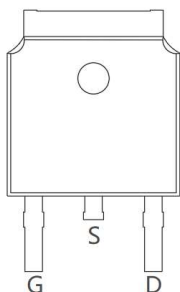
- 650 V enhancement mode power switch
- $R_{DS(on)} = 160 \text{ m}\Omega$
- $I_{DS(max)} = 10 \text{ A}$
- Easy gate drive requirements (0 V to 6 V)
- Very high switching frequency (> 10 MHz)
- Fast and controllable fall and rise times
- Zero reverse recovery loss

## 2. Device Information

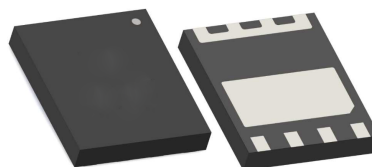
Part Number	Marking Code	Package	Packing
HN65H10R160	HN6510R	TO252	Tape 2.5k/reel
HN65H10Q160	HN6510Q	DFN5x6	Tape 3k/reel
HN65H10D160	101YWWXX	PDDFN4x4	Tape 3k/reel
HN65H10S160	HN6510S	DFN8x8	Tape 3k/reel



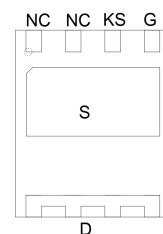
TO252



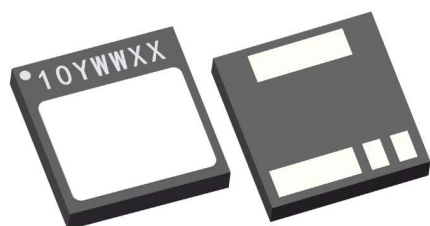
Top View



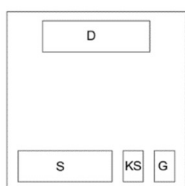
DFN5x6



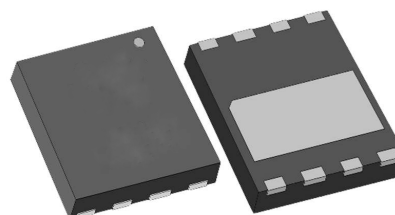
Bottom View



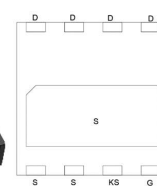
PDDFN4x4



Bottom View



DFN8x8



Bottom View

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### 3. Applications

- Fast Battery Charging
- LED lighting drivers
- Power Factor Correction
- LLC Converters
- Wireless Power Transfer

### 4. Description

HN65H10x160 is an enhancement mode GaN-on-silicon transistor. GaN is a wide band gap semiconductor with high power density. The gallium nitride transistor is characterized by no body diode, so the reverse recovery charge is zero. There are four packages (TO252, DFN5x6 ,PDDFN4x4 and DFN8x8) for customers to choose. It is specially stated that PDDFN4x4 is the world's smallest 650V E-Mode GaN HEMT independently developed by our company. It has a double-sided heat dissipation function and can be connected to an external heat sink. It adopts RDL assembly process and has extremely low parasitic resistance and inductance, so it is particularly suitable for high High-frequency and high-power applications

### 5. Absolute Maximum Ratings ( $T_c=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit	Condition
Drain-Source voltage	$V_{DS}$	650	V	
Gate-source voltage	$V_{GS}$	-10 to 6	V	
Continuous drain current*	$I_D$	10	A	$T_c=25^{\circ}\text{C}$
		8	A	$T_c=100^{\circ}\text{C}$
Operation and storage temperature	$T_j$	-55 to 150	$^{\circ}\text{C}$	
	$T_{stg}$	-55 to 150	$^{\circ}\text{C}$	

\* An Estimated Value

## 6. Electrical Characteristics (T<sub>c</sub>=25°C unless otherwise specified)

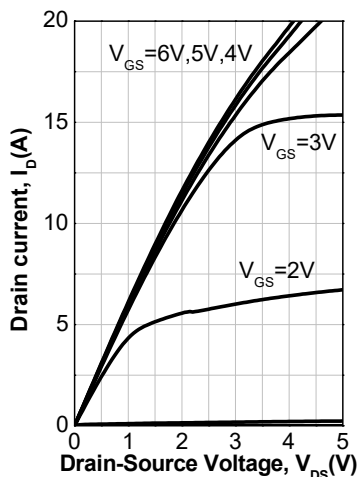
### 6.1 Typical Performance – Static

Parameter	Symbol	Values			Unit	Test condition
		Min.	Type.	Max.		
Drain source breakdown voltage	BV <sub>DS</sub>	650	/	/	V	VGS=0V, ID=20μA
Total drain leakage current	I <sub>DSS</sub>	/	/	10	μA	VDS=650V, VGS=0V, Tj=25°C
		/	/	50	μA	VDS=650V, VGS=0V, Tj=150°C
Gate-to-source current	I <sub>GS</sub>	/	100	/	μA	VDS=0V, VGS=6V, Tj=25°C
		/	500	/	μA	VDS=0V, VGS=6V, Tj=150°C
Static drain-source on-resistance	R <sub>DS(ON)</sub>	/	160	/	mΩ	VGS=6V, ID=5A, Tj=25°C
		/	370	/	mΩ	VGS=6V, ID=5A, Tj=150°C
Gate threshold voltage	V <sub>GS(th)</sub>	0.8	/	1.2	V	VDS=VGS, ID=3.5mA,

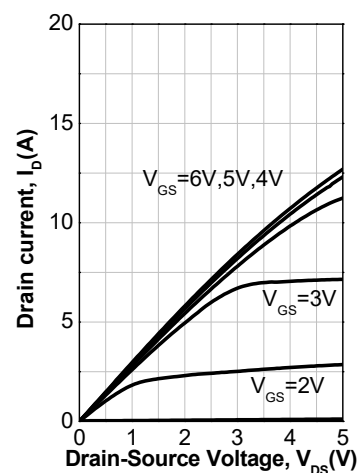
## 6.2 Typical Performance – Dynamic

Parameter	Symbo	Values			Unit	Test condition
		Min	Type	Max		
Input capacitance	$C_{iss}$	/	60	/	pF	$V_{DS}=400V$ , $V_{GS}=0V$ , $f=1MHz$
Output capacitance	$C_{oss}$	/	24	/	pF	
Reverse transfer capacitance	$C_{rss}$	/	0.7	/	pF	
Output capacitance, energy related	$C_{oss(er)}$	/	34	/	pF	$V_{DS}=0V$ to 400V, $V_{GS}=0V$
Output capacitance time related	$C_{oss(tr)}$	/	44	/	pF	
Total gate charge	$Q_G$	/	2.0	/	nC	$V_{DS}=400V$ , $V_{GS}=0V$ to 6V
Gate-drain charge	$Q_{GD}$	/	0.9	/	nC	
Gate-source charge	$Q_{GS}$	/	0.4	/	nC	
Gate Resistance	$R_G$	/	0.69	/	$\Omega$	$f = f_{res}$ , Open drain

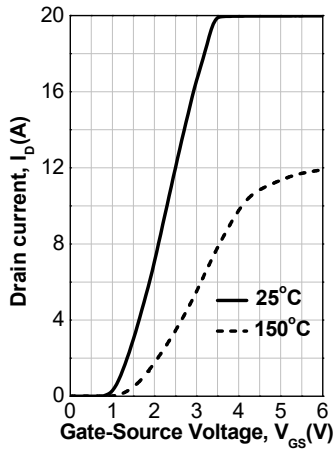
## 6.3 Characteristic Curve



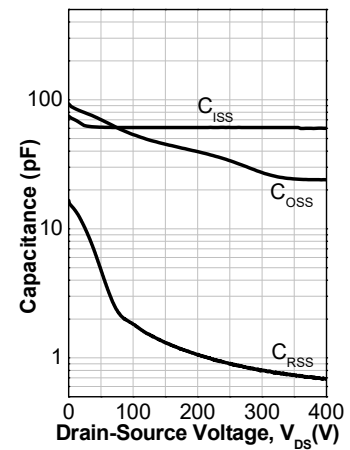
Typical output characteristics @  $T_j=25^\circ C$



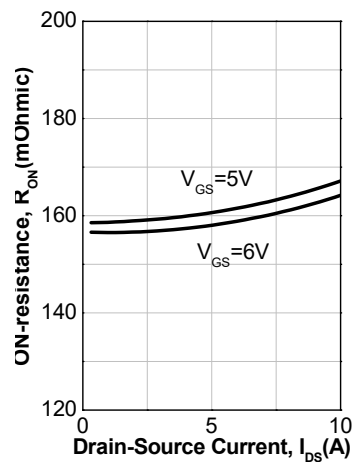
Typical output characteristics @  $T_j=150^\circ C$



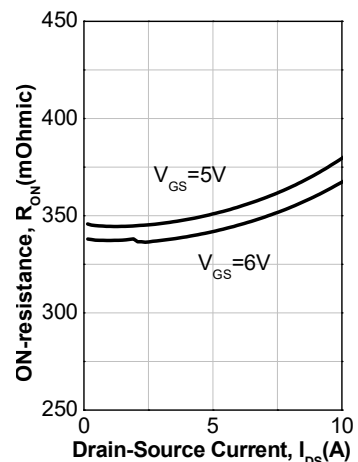
Typical transfer characteristics @  $V_{DS}=5V$



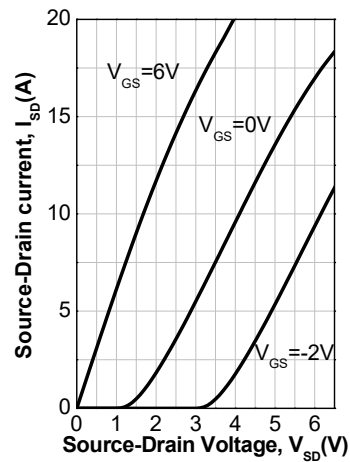
Typical capacitance characteristics @ 1MHz



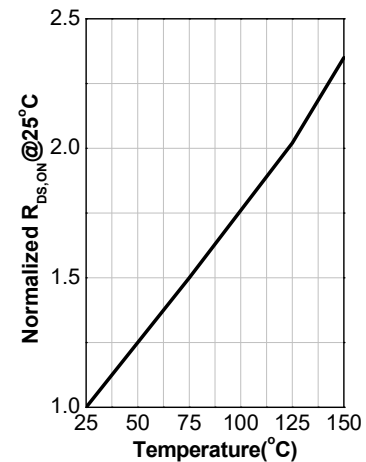
ON-resistance for various drain current @ 25°C



ON-resistance for various drain current @ 150°C



Typical reverse conduction characteristics

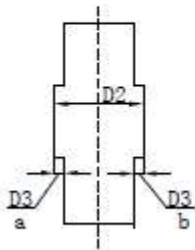
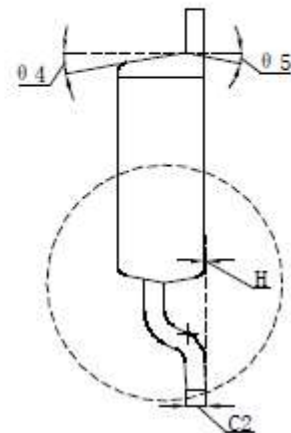
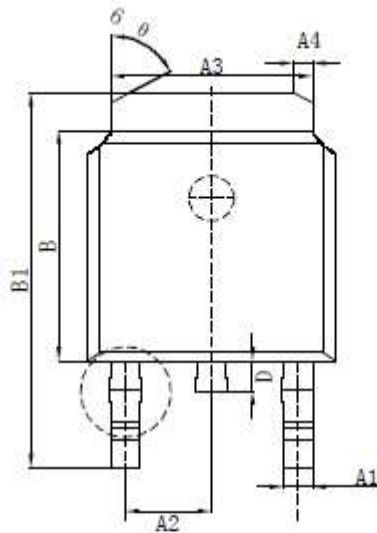
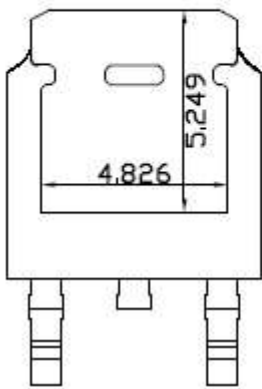


Normalized ON-resistance at various temperatures

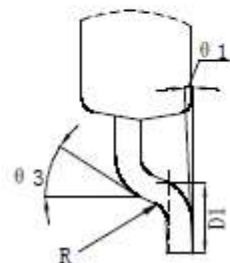
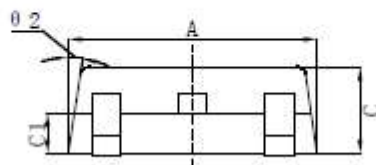
## 7. Package

### 7.1 TO252

标注	尺寸	最小(mm)	最大(mm)	标注	尺寸	最小(mm)	最大(mm)
A		6.50	6.70	D1		1.40	1.60
A1		0.71	0.81	D2		0.81	0.91
A2		2.236	2.336	D3		0.05TYP	
A3		5.284	5.384	H		0.00	0.10
A4		0.75	0.85	R		0.40TYP	
B		6.00	6.20	θ 1		0° — 8°	
B1		9.80	10.10	θ 2		8.5° TYP4	
C		2.20	2.40	θ 3		25° TYP	
C1		0.967	1.087	θ 4		10° TYP2	
C2		0.498	0.518	θ 5		10° TYP	
D		0.70	0.90	θ 6		70° TYP	

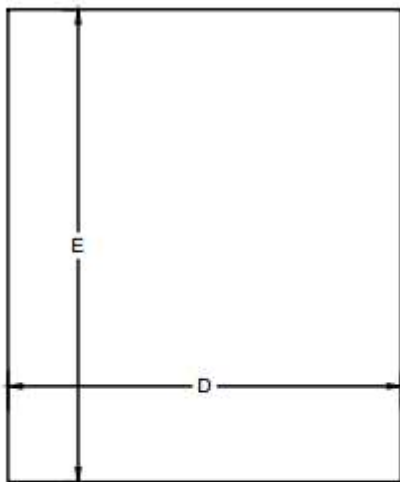


$0 < a, b < 0.1$

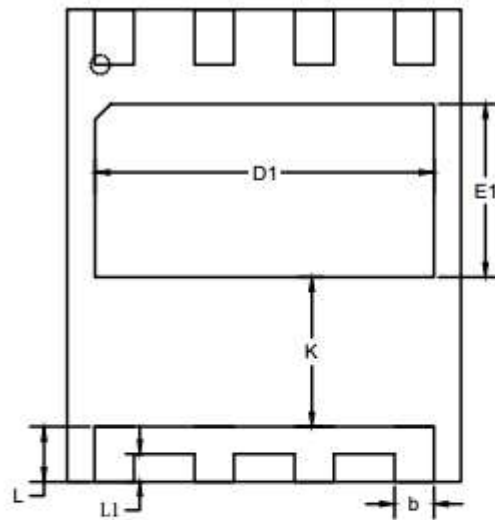


## 7.2 DFN5x6

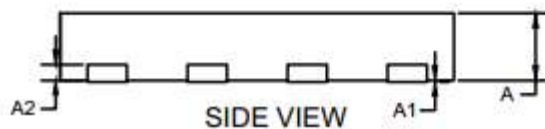
尺寸对照表(单位: mm)			
	Min.	Nom.	Max.
A	0.80	0.85	0.90
A1	-	0.02	0.05
A2	0.2(REF)		
b	0.45	0.50	0.55
D	4.90	5.00	5.10
D1	4.20	4.30	4.40
E	5.90	6.00	6.10
E1	2.10	2.20	2.30
e	1.27		
k	1.9	-	-
L	0.65	0.7	0.75



TOP VIEW



BOTTOM VIEW

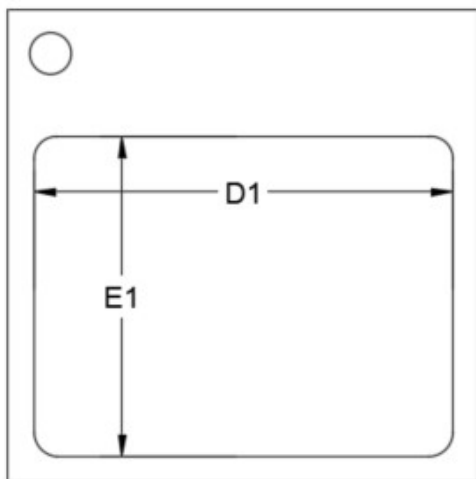


SIDE VIEW

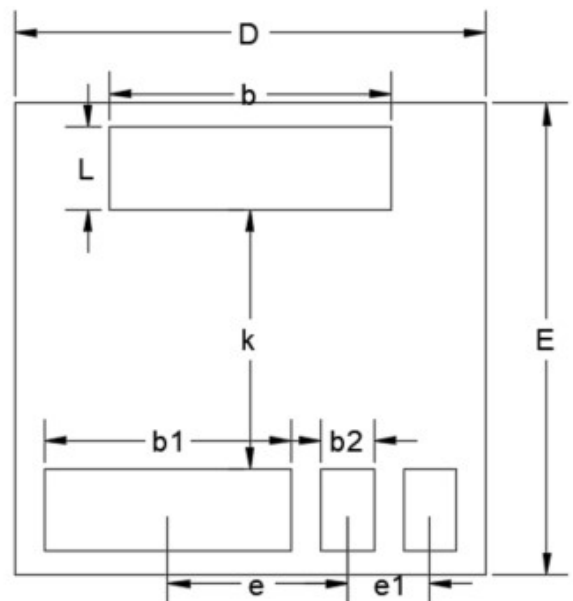


### 7.3 PDDFN4x4

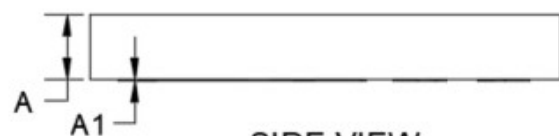
尺寸对照表Dimensions(mm)			
符号Symbol	最小值Min	典型值Typ	最大值Max
A	0.50	0.55	0.6
A1	0.007	0.012	0.017
b	2.35	2.4	2.45
b1	2.05	2.1	2.15
b2	0.4	0.45	0.5
D	3.9	4	4.1
D1	3.45	3.55	3.65
E	3.9	4	4.10
E1	2.62	2.72	2.82
e	REF 1.525		
e1	REF 0.7		
k	REF 2.2		
L	0.65	0.7	0.75



TOP VIEW



BOTTOM VIEW



SIDE VIEW

## 7.4 DFN8x8

Dimensions(mm)			
Symbol	Min	Typ	Max
A	0.80	0.9	1
A1	REF 0.203		
b	0.95	1	1.05
D	7.9	8	8.1
D1	6.9	7	7.1
E	7.9	8	8.10
E1	3.1	3.2	3.30
e	REF 2		
k	REF 2.8		
L	0.45	0.5	0.55

